

## CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8

BRINKS HOFER GILSON &LIONE

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re	Appln. of:		— —	ibokawa et al.	-INT AINE	, ,,,,				OL .		
Appln. No.:		10/676,939						Examiner: J. Johnson				
Filed:		October 1, 2003						Art Un	it:	1725		•
For:		Solder Joint Structure and Method for Soldering Electronic Components										
Attorney Docket No: 9281/4702												
Mail Stop Amendment Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450  TRANSMITTAL												
Sir:												
Attached is/are:												
<ul> <li>☑ Transmittal Cover Letter (1p.); Supplemental Preliminary Amendment (3pp.)</li> <li>☑ Return Receipt Postcard</li> </ul>												
Fee calculation:  No additional fee is required.												
	<u> </u>											
<ul> <li>A petition or processing fee in an amount of \$ under 37 C.F.R. § 1.17().</li> <li>An additional filing fee has been calculated as shown below:</li> </ul>												
	An additiona	ai filing fee	e nas be	een calculated as sr	iown belov	v:			Γ	Not a S	mall E	atity
	Claims Re	maining		Highest No.	Present	<del>   </del>	Silie	III Entity		Not a S	man Ei	iuty
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Fee payment:												
A check in the amount of \$ is enclosed.												
	Please charge Deposit Account No. 23-1925 in the amount of \$ . A copy of this Transmittal is enclosed for this purpose.											
	Payment by credit card in the amount of \$ (Form PTO-2038 is attached).											
The Director is hereby authorized to charge payment of any additional filing fees required under 37 § 1.16 and any patent application processing fees under 37 CFR § 1.17 associated with this payment, including any extension fee required to ensure that this paper is timely filed), or to credit overpayment, to Deposit Account No. 23-1925.									paper			

Respectfully submitted,

Anthony P. Curtis, Ph.D. (Reg. No. 46,193)

APW

Finereby certify that this correspondence is being deposited with the United States Postal Service, with sufficient postage, as first class mail in an envelope addressed to:

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Date of Deposit

Anthony P. Curtis, Ph.D., 46,193

Name of applicant, assignee or Registered Representative

/ Signature

Date of Signature

Our File No. 9281-4702

Client No. S US02113

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:						
Teru	yoshi Kubokawa et al.	)				
Serial No. 10/676,939						
Filing Date: October 1, 2003						
For	Solder Joint Structure and Method for Soldering Electronic Components	)				

## SUPPLEMENTAL PRELIMINARY AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Prior to examination of the above-identified application, please amend the application as follows:

Amendments to the Specification begin on page 2 of this paper.

Remarks begin on page 3 of this paper.